

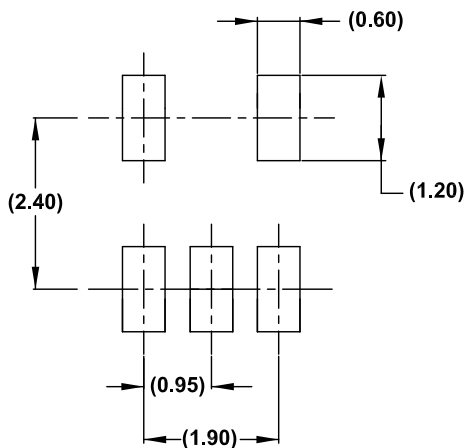
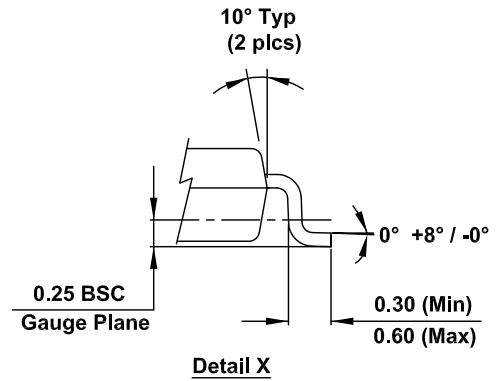
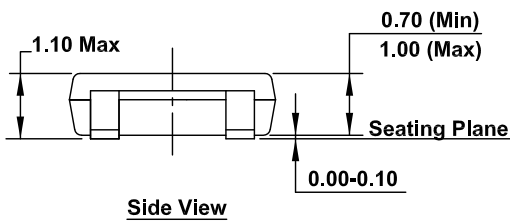
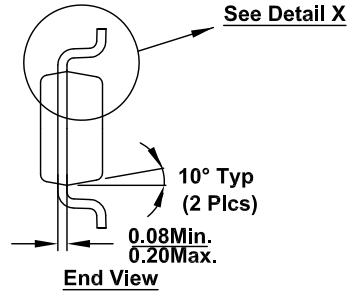
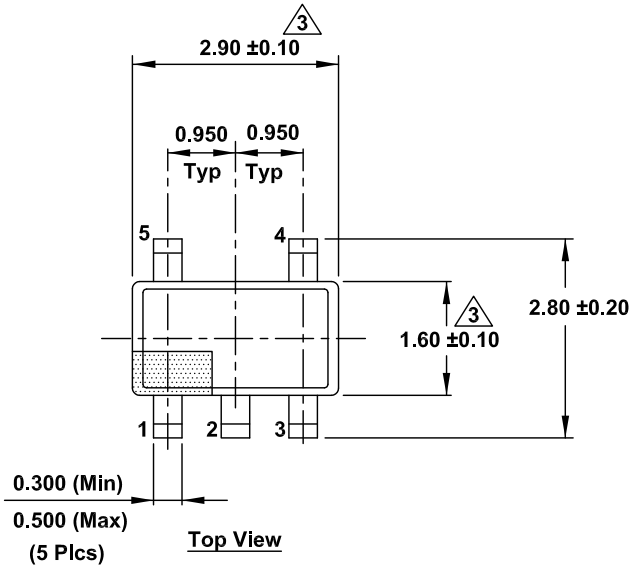
Plastic Packages for Integrated Circuits

Package Outline Drawing

P5.064B

5 Lead Thin Small Outline Transistor (TSOT) Plastic Package

Rev 3, 2/2022



Typical Recommended Land Pattern

NOTE:

1. Dimensioning and tolerancing conform to ASME Y14.5m-1994.
2. Die is facing up for mold. Die is facing down for trim/form, that is reverse trim/form.
3. Dimensions are exclusive of mold flash and gate burr.
4. The footlength measuring is based on the gauge plane method.
5. All specifications comply to JEDEC Spec MO193 Issue C.